

We Claim:

- 1 1. A device for cooling memory modules comprising:
 - 2 a plurality of elements, the elements thermal coupling at least two memory
 - 3 modules.

- 1 2. The device as claimed in claim 1, comprising:
 - 2 a body, the body being comb-shaped in longitudinal section.

- 1 3. The device as claimed in claim 1, comprising:
 - 2 a plurality of contact areas bearing in a planar manner.

- 1 4. The device as claimed in claim 3, wherein the contact areas are connected to
 - 2 the body via spring elements.

- 1 5. The device as claimed in claim 2, wherein the body is formed of aluminum.

- 1 6. The device as claimed in claim 5, wherein an insulation layer is formed at
 - 2 least partially on the surface of the contact areas.

- 1 7. The device as claimed in claim 2, wherein the body has cooling fins.

1 8. The device as claimed in claim 2, wherein the basic body has a fan as an
2 active cooling element.

1 9. The device as claimed in claim 2, wherein the body has a Peltier element as
2 an active cooling element.

1 10. The device as claimed in claim 8, wherein the active cooling element is
2 embedded in a temperature regulating circuit.

1 11. The device as claimed in claim 9, wherein the active cooling element is
2 embedded in a temperature regulating circuit.